ENGINEERING DEPT.	**PRODUCT SPECIFICATION** **For Pitch 1.27mm(.050") Pin Header of System CHC2**	**SPEC.NO.: SPCH037C** **PAGE: 1/3**

1. SCOPE:

This specification contains the test requirement of subject pin headers when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
MIL - STD - 1344	Test methods for electrical connectors
JIS - C - 5402	Methods for test of connectors for electronic equipment
UL 94	Test for flammability of plastic materials for parts in devices and appliance
J-STD-020	Resistance to soldering Temperature for through hole Mounted Devices
SS-00254	Test methods for electronic components ,LEAD-FREE soldering Part design standards

3. APPLICABLE SERIES No. : **CHC2 Series**

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

(P.C. Board on which the Pin Header are installed), 1.6 mm (.063″)

CVILUX.CORP.
2007.01.17
ISSUED

REVIEWED : Alex APPROVED : David VERIFIED : Sun .

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7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	
7.1	Rated current and voltage		1.5A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 100 mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 600 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 1000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Pin retention force	Push pin from insulator base at speed 25± 3 mm per minute	Square Pin : 0.3 Kgf (2.94 N) Min. Round Pin : 0.6 Kgf (5.88 N) Min.

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Solder ability	Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5°C	Minimum: 90% of immersed area
9.2	Resistance to soldering heat	**DIP Type:** Soldering time: 5 ± 0.5 second Soldering pot: 260 ± 5°C **SMT Type:** Soldering time: 20 second Max. Soldering pot: 250~260°C	No damage
9.3	Heat aging	105± 2°C, 96 hours	No damage
9.4	Humidity	40± 2°C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3

	ITEM	TEST CONDITION	REQUIREMENT
9.5	Temperature cycling	One cycle consists of : (1)-55^{+0}_{-3} °C , 30 min. (2)Room temp. 10-15 min. (3) 85^{+3}_{-0} °C , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial
9.6	Salt spray	Temperature: 35± 3°C Solution: 5± 1% Spray time: 48± 4 hours Measurement must be taken after water rinse	Appearance: No damage Contact resistance: Less than twice of initial

10. AMBIENT TEMPERATURE RANGE: -40 to + 105°C

11. Recommended IR Reflow Temperature Profile: